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ATTORNEY DOCKET NO. CONFIRMATION NO. APPLICATION NO. FIRST NAMED INVENTOR FILING DATE TS01-045 7509 09/992.458 11/16/2001 Wong-Cheng Shih

7590 05/08/2003 28112 GEORGE O. SAILE & ASSOCIATES 28 DAVIS AVENUE POUGHKEEPSIE, NY 12603

EXAMINER DOAN, THERESA T ART UNIT PAPER NUMBER

2814 DATE MAILED: 05/08/2003

Please find below and/or attached an Office communication concerning this application or proceeding.

Office Action Summary	Application No.	Applicant(s)
	09/992,458	SHIH ET AL.
	Examiner	Art Unit
	Theresa T Doan	2814
The MAILING DATE of this communication Period for Reply	appears on the cover sheet w	ith the correspondence address
A SHORTENED STATUTORY PERIOD FOR RI THE MAILING DATE OF THIS COMMUNICATIC Extensions of time may be available under the provisions of 37 Cl after SIX (8) MONTHS from the mailing date of this communicatio If the period for reply specified above is less than thirty (30) days, If a pailure to reply specified above is less than thirty (30) days, Failure to reply with the set or extended period for reply will, by a Any reply received by the Morio later than three months after the r aarmed patent term adjustment. See 37 CFR 1.704(b). Status	DN. FR 1.136(a). In no event, however, may a in. a reply within the statutory minimum of thir eriod will expire SIX (6) MOh statute, cause the application to become AI	reply be timely filed ty (30) days will be considered timely. ITHS from the mailing date of this communication. BANDONED (35 U.S.C.§ 133).
1) Responsive to communication(s) filed on	15 April 2003 .	
2a) ☐ This action is FINAL . 2b) ☑	This action is non-final.	
Since this application is in condition for all closed in accordance with the practice un Disposition of Claims		
4) Claim(s) 1-23 is/are pending in the application	ation.	
4a) Of the above claim(s) 21-23 is/are with	drawn from consideration.	
5) Claim(s) is/are allowed.		
6)⊠ Claim(s) <u>1-20</u> is/are rejected.		
7) Claim(s) is/are objected to.		
8) Claim(s) are subject to restriction are	nd/or election requirement.	
Application Papers		
9) The specification is objected to by the Exam		
10) The drawing(s) filed on is/are: a) a	· · · · ·	
Applicant may not request that any objection t		• • •
11) The proposed drawing correction filed on If approved, corrected drawings are required in		isapproved by the Examiner.
12) The oath or declaration is objected to by the		
Priority under 35 U.S.C. §§ 119 and 120	s Examiner.	
13) Acknowledgment is made of a claim for for	reign priority under 25 II C C 8	S 110(a) (d) ar (5)
a) ☐ All b) ☐ Some * c) ☐ None of:	org., priority under 55 0.5.0.	3 110(a)-(u) 01 (1).
1. Certified copies of the priority docum	nents have been received	
Certified copies of the priority docum		onlication No
3. Copies of the certified copies of the		
application from the International * See the attached detailed Office action for a	Bureau (PCT Rule 17.2(a)). list of the certified copies not	received.
14) Acknowledgment is made of a claim for dom		
 a) The translation of the foreign language 15) Acknowledgment is made of a claim for dom 		
Attachment(s)		
Notice of References Cited (PTO-892)) 5) Notice of I	Summary (PTO-413) Paper No(s) Informal Patent Application (PTO-152)

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DETAILED ACTION

Request for Continued Examination

1. A request for continued examination under 37 CFR 1.114, including the fee set forth in 37 CFR 1.17(e), was filed in this application after final rejection. Since this application is eligible for continued examination under 37 CFR 1.114, and the fee set forth in 37 CFR 1.17(e) has been timely paid, the finality of the previous Office action has been withdrawn pursuant to 37 CFR 1.114. Applicant's submission filed on 04/11/03 has been entered. An action on the RCE follows.

The amendment filed on 02/10/03 has been entered.

Information Disclosure Statement

The information disclosure statement (IDS) submitted on 02/10/03, which is being considered by the examiner.

Claim Rejections - 35 USC § 112

3. The following is a quotation of the first paragraph of 35 U.S.C. 112:

The specification shall contain a written description of the invention, and of the manner and process of making and using it, in such full, clear, concise, and exact terms as to enable any person skilled in the art to which it pertains, or with which it is most nearly connected, to make and use the same and shall set forth the best mode contemplated by the inventor of carrying out his invention.

 Claims 21-23 are rejected under 35 U.S.C. 112, first paragraph, as containing subject matter which was not described in the specification in such a way as to

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reasonably convey to one skilled in the relevant art that the inventor(s), at the time the application was filed, had possession of the claimed invention.

The limitations of "wherein said first wide-band-gap insulating layer and said second wide-band-gap insulating layer have a band-gap that is greater than about 8.0 electron volts (eV)", as recited in claims 21-23, are not supported in the original disclosure

Claim Rejections - 35 USC § 103

 The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior at are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be neadtived by the manner in which the invention was made.

 Claims 1-2, 4, 8 and 16-19 are rejected under 35 U.S.C. 103(a) as being unpatentable over Alers et al. (6,320,244) as previously cited in view of Liou et al. (6,017,790).

Regarding claims 1 and 16, Alers et al. teach in figure 9 a method for making a metal-insulator-metal capacitor on a substrate 30 comprising the steps of:

forming bottom electrode 44 from a first conducting layer on the substrate; depositing a first TiO2 insulating layer 64 on the bottom electrode; depositing a multi-layer of high-k dielectric film 66 over the insulating layer 64; depositing a second TiO2 insulating layer 68 over the multi-layer; forming top electrode 48 from a second conducting layer on the second

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insulating layer 68.

Alers et al. do not explicitly show the first and second TiO₂ insulating layers (64,68) are wide-band-gap. However, Liou et al. in column 4, lines 45-48 teach a metal oxide such as titanium oxide (TiO₂) is a wide-band-gap insulating material. Therefore, the first and second TiO₂ insulating layers (64,68) of Alers device, which are considered as wide-band-gap insulating layers. Thus, Alers et al.'s structure is considered to be at least obvious over the claimed structure.

Regarding claims 2, 8 and 18, Alers et al. teach in figure 9, wherein the bottom electrode 44 and the top electrode 48 are made of titanium nitride (column 4, lines 48-50 and column 5, lines 15-16). Alers et al. do not explicitly teach a range of thickness of bottom and top electrodes about 200-1000 Angstroms and a thickness of the high-k dielectric film about 50 and 800 Angstroms. However, in the text of Alers et al. teach a range of thickness can vary depending on the thickness desired (column 7, lines 47-48 and lines 56-59) in order to operate the device in its intended use. Therefore, it would have been obvious to a person of ordinary skill in the art at the time the invention was made to use a thickness of the bottom and top electrodes and the high-k dielectric film in Alers's device as suggested by instant invention in order to operate the device in its intended use.

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Regarding claims 4 and 19, Alers et al. teach the high-k dielectric film is a material selected from the group that includes tantalum pentoxide (figure 9, column 5, lines 12-13 and column 1, lines 43-46).

Regarding claim 17, Alers et al. teach the bottom electrode and the top electrode are made of the group that includes titanium nitride (figure 9, column 4, lines 48-50 and column 5, lines 15-16).

7. Claims 3, 5-7, 9-15, and 20 are rejected under 35 U.S.C. 103(a) as being unpatentable over Alers et al. (6,320,244) in view of Yoon et al. (5,688,724) as previously cited.

Regarding claims 3, 10 and 12, as discussed above, Alers et al. teach in figure 9 a method for making a metal-insulator-metal capacitor on a substrate 30 comprising the steps of:

forming bottom electrode 44 that composed of titanium nitride on the substrate (column 4, lines 48-50);

depositing a first ${\rm TiO_2}$ wide-band-gap insulating layer 64 on the bottom electrode (column 7, lines 29-32);

depositing a tantalum pentoxide high-k dielectric film 66 over the wideband-gap insulating layer (figure 9, column5, lines 12-13 and column 1, lines 43-46);

depositing a second TiO_2 wide-band-gap insulating layer 68 over the high-k dielectric film (column 7. lines 35-39):

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forming top electrode 48 that composed of titanium nitride over the second wide-band-gap insulating layer (figure 9, column 5, lines 15-16).

Alers et al. do not teach an aluminum oxide for the first and second wide-band-gap insulating layers. However, Yoon et al. teach in figure 21 the material of dielectric layers includes SiO₂, TiO₂, Si₃N₄ and Al₂O₃ (column 11, lines 12-15) for the isolation purpose. Therefore, it would have been obvious to substitute Al₂O₃ insulating layer for TiO₂ insulating layer in Alers et al. Because the substitution of art recognized equivalent as suggested by Yoon et al. is within the level of ordinary skill in the art.

Regarding claims 11 and 13, Alers et al. teach substantially the entire claimed structure, as applied to claim 10 above, except for a thickness of the high-k dielectric film about 50 and 800 Angstroms and a range of thickness of bottom and top electrodes about 200-1000 Angstroms. However, in the text of Alers teaches a range of thickness can vary depending on the thickness desired (column 7, lines 47-48 and lines 56-59) in order to operate the device in its intended use. Therefore, it would have been obvious to a person of ordinary skill in the art at the time the invention was made to use a thickness of the bottom and top electrodes and the high-k dielectric film in Alers's device as suggested by instant invention in order to operate the device in its intended use.

Regarding claims 5-7 and 14, it is well known that the high-k dielectric film is deposited by methods of physical vapor deposition, chemical vapor deposition and

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atomic layer chemical vapor deposition as taught by Alers and Yoon in order to operate the device in its intended use.

Regarding claims 9, 15 and 20, Alers et al. teach substantially the entire claimed structure, as applied to claims 1, 10 and 16 above, except for the high-k dielectric film is treated in a gas selected from the group that includes oxygen, nitrogen, nitrous oxide, and ammonia, and rapid thermally annealed at a temperature of between about 300 and 700°C for a time of between about 1 and 260 seconds.

Yoon et al. teach a high-k dielectric film 14 is treated in a gas selected from the group that includes oxygen and rapid thermally annealed at a temperature of between about 400-550°C for a time of five minutes (column 4, lines 19-25) in order to reduce leakage current in a dielectric structure. Therefore, it would have been obvious to one of ordinary skill in the art at the time of invention was made to modify the Alers et al. structure using the method of Yoon in order to reduce leakage current in a dielectric structure.

Claims 1 and 16 are rejected under 35 U.S.C. 103(a) as being unpatentable over
 Hisatomi et al. (6,163,050) in view of Ovshinsky et al. (4,766,471).

Regarding claims 1 and 16, Hisatomi et al. teach in figure 2 a method for making a metal-insulator-metal capacitor on a substrate 33 comprising the steps of:

forming bottom electrode 35 from a first conducting layer on the substrate; depositing a first SiO₂ insulating layer 36-1 on the bottom electrode;

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depositing a multi-layer of high-k dielectric film 36-2 over the insulating layer; depositing a second SiO₂ insulating layer 36-3 over the multi-layer;

forming top electrode 37 from a second conducting layer on the second insulating layer.

Hisatomi et al. do not explicitly show the first and second SiO₂ insulating layers (36-1,36-3) are wide-band-gap. However, Ovshinsky et al. in column 29, lines 61-62 teach an insulating material such as silicon oxide having a very wide-band-gap. Therefore, the first and second silicon oxide insulating layers of Hisatomi device are considered as wide-band-gap insulating layers.

Response to Arguments

Applicant's arguments with respect to claims 1-20 have been considered but are moot in view of the new ground(s) of rejection.

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Theresa T Doan whose telephone number is (703) 305-2366. The examiner can normally be reached on Monday to Thursday from 8:00AM - 6:00PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, WAEL FAHMY can be reached on (703) 308-4918. The fax phone numbers

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for the organization where this application or proceeding is assigned are (703) 308-7722 for regular communications and (703) 308-7724 for After Final communications.

Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the receptionist whose telephone number is (703) 308-0956.

TD April 28, 2003 CANMAN MAL PHAT X. CAO PRIMARY EXAMINER